

Date: 29/01/2025

**To,
The General Manager,
Listing Department,
BSE Limited
Phiroze Jeejeebhoy Towers
Dalal Street, Mumbai- 400 001**

BSE CODE: 504346

SUBJECT: Disclosure of material event under regulation 30 of SEBI (LODR) Regulations, 2015.

Dear Sir,

With reference to above cited subject we would like to disclose following:

In one of the most ambitious plans, to create a greater impact on the society, RRP semiconductor Limited has entered into the Fabless world.

The officials of the company recently visited to Europe followed by interaction with their technology partners has fructified into ownership of complete IP transfer of ASICS design, which will enable them to enter independently into the discrete semiconductor market.

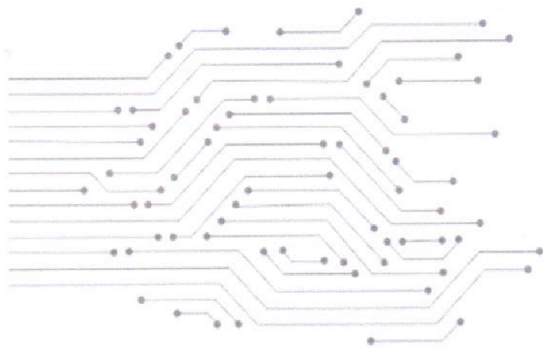
With its group companies and consortium already equipped with OSAT packaging facilities and commencement of journey, into Fab prototyping, RRP semiconductor Limited promises to offer a One umbrella solution in the field of Semi-Conductor.

The ASICS design competence allows them to penetrate deeply into design and manufacture of various automotive components and chips, in huge numbers.

These, to the best of our knowledge are presently being imported, thereby opening up a ready market opportunities estimated to be starting from 25 MusD to over 100 MusD within 2 years of deployment

ASIC (An application -specific integrated circuit is an integrated circuit (IC) chip customised for general purpose use, such as a chip designed to run a digital voice recorder or a high efficiency video codec

These product chips are an intermediate between ASICS and industry standard integrated circuits viz 7400 series or the 4000 series



ASIC chips are typically fabricated using metal -oxide-semiconductor technology.

Modern ASIC includes entire microprocessors including ROM, RAM, EEPROM, flash memory and other building blocks often termed as System on chips (SoC) thereby plunging into the strategic applications too

With the ASIC market estimated to reach over USD 30 billion by 2031, growing at a compound annual growth rate (CAGR) of 7.10% from 2031 to 2034, this technology possession promises a ready business opportunity of 25 musd in the forth coming financial year which promises quantum jumps in revenues within 2 years of deployment.

By possessing this technology, a basic idea proposed by the customer will allow RRP Semiconductor to design a complete lay out of a chip, to be offered to Fab company for wafer design.

The total IP transfer will cover :

1. Guidance/training/know how for
2. ASIC development workflow
3. Specifications and requirements gathering
4. Front end design covering
5. RTL coding
6. Verification
7. Synthesis
8. Back end designing covering DRC,LVS , extraction
9. Tape out procedures
10. Tools and infrastructure
11. Selection of EDA tools and licensing requirements
12. Setting up of computing infrastructure
13. Lab and test set up
14. Documentation standards
15. Project Management



16. Risk Management
17. Time line management
18. Workshops on front end and back-end design techniques
19. Real world case studies

For RRP SEMICONDUCTOR LIMITED

(Formerly known as G D Trading and Agencies Limited)

Ramesh Chandra Mishra
Director
DIN: 00206671

